environment.  29. a. Illustrate the platform FPGA components in detail.  (OR)  b. Explain with an example to illustrate the different ways components can be combined to form large modules.			2,4 ,1 2,3 ,1
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(OR)  b. Explain with an example to illustrate the different ways components can be combined to form large modules.	2	4	2,3 ,1
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combined to form large modules.			
10	3	4	3,2 ,1
30. a. Interpret the different levels of parallelism in detail.	2	5	2,3 ,1
(OR)			
b. Define profiling and explain the practical issues faced during profiling.	2	5	1,4 ,1

\* \* \* \* \*

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Reg. No.				S				

## B.Tech. DEGREE EXAMINATION, NOVEMBER 2022

Sixth and Seventh Semester

## 18ECE205J – FPGA-BASED EMBEDDED SYSTEM DESIGN

(For the candidates admitted from the academic year 2018-2019 to 2019-2020)

Note: (i)	Par	t - A should be answered in OM	Sheet v	vithin first 40 minutes and OMR shee	et shou	ld be	han	ded
(1)		r to hall invigilator at the end of 40	_		onou	14 00	11011	aoa
(ii)		t - B should be answered in answe						
Time: 2	½ Ho	urs			Max	. Ma	rks:	75
		PART – A (25 ×	1 = 25 I	Marks)	Marks	BL	со	PO
		Answer ALL						
1.	Whi	ich design allows the reuse of s	oftware	and the hardware components?	1	2	1	4
	(A)	Memory design	(B)	Input design				
	(C)	Platform based design	(D)	Peripheral design				
2.		configuration has memory.	s only c	one "zero" location for both data	1	1	1	1
		Von Neumann memory	(B)	Harvard memory				
		Memory	(D)	CPU				
3.	The	maximum size of the external	data me	emory space isbytes.	1	1	1	1
	(A)		(B)					
	(C)		(D)					
4.		ich design can be used to nedded system?	educe	the energy consumption of the	1	1	1	1
		Simulator	(B)	Compiler				
	(C)	Emulator	(D)	Debugger				
5.		technique where by the DMA tessor to operate is called	control	ler steals the access cycles of the	1	1	1	1
	(A)	Fast conning	(B)	Memory con				
	(C)	Cycle stealing	(D)	Memory stealing				
6.	FPG	GA device aretypes			1	1	2	2
	(A)	PLD	(B)	EPROM .				
	(C)	SROM	(D)	SLD				
7.		w many logic gates can be igrammable logic devices?	mpleme	ented in the circuit by complex	1	2	2	2
	(A)	<del>-</del>	(B)	100				
		1000	(D)	10000				
	` /		. ,					

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8.	<ul><li>Which among the following are use inputs?</li><li>(A) Input buffers</li><li>(C) Or matrix</li></ul>	ed in PAL for reducing the loading on  (B) Output buffers  (D) And matrix	1	1	2	2		19.	a (A	hich type of simulation mode is used to check the timing performance of lesign?  (B) Switch level (D) Gate level	1	2	5	2
9.	In DMA transfers, the required signal (A) Processor (C) DMA controllers	gnals and addresses are given by the  (B) Device drivers  (D) The program itself	1	1	2	1	v	·20.	lea	hich type of digital system exhibit the necessity for the existence of at st one feedback path from output to input?  (B) Sequential system (D) Drive attribute	1	2	5	
10.	Which interrupt is unmaskable? (A) RST 5.5 (C) TRAP	(B) RST 7.5 (D) Both RST 5.5 and 7.5	1	1	2	2		21.	(A	e coprocessor model is also known as  (B) Multithread model  (Network onchip model (D) Single thread model	1	2	6	2
11.	Identify the variant in XILINX 5 virgorocessing applications  (A) SX  (C) TX	tex IDE that is mainly for digital signal  (B) LX  (D) FX	1	2	3	1		22.	ca (A	process network is a design abstraction in which functional components led processes communicate through data items called	1	2	5	
12.	An embedded system has(A) Response time constraints (C) Turn around time	<ul><li>(B) Strict deadlines</li><li>(D) Response time constraints and strict deadlines</li></ul>	1	2	3	2		23.	an	Sequential (B) Combinational	1	2	6	:
	Configurable logic blocks in FPGA a (A) Look up tables (C) Carry look ahead logic	<ul><li>(B) Programmable interconnect</li><li>(D) Logic cell</li></ul>	1	2	3	1		24.	dit (A	e function based ESL design method uses model to compose ferent functional components into a complete system.  (B) Computational (C) Communication  (D) Sequential	1	2	5	2
14.	In FPGA, provides interfa (A) Input output blocks (C) Simulator	ce between package pins and CLBs.  (B) Functional blocks  (D) Synthesis	1	2	3	2		25.	Ho tri	Id time is defined as the time required for the data toafter the gering edge of clock.  (B) Decrease	1	2	5	-
15.	array is called(A) PLD	ray and array and a programmable OR  (B) PROM	1	2	3	1			(C	Hold (D) Remain stable	= 2.			
16.		(D) PLA separately compiled modules of a	1	2	4	2				$PART - B (5 \times 10 = 50 Marks)$ Answer ALL Questions	Marks	BL	со	P
	program into a form suitable for exect (A) Assembler (C) Cross compiler	cution is called  (B) Linking loader  (D) Debugger					ā	26. a.		monstrate and explain various types of mechanisms in interrupt service adling process and the need of DMA in embedded systems.	10	2	1	2,
17.	In VLSI design, which process deal capacitance of interconnections?	s with determination of resistance and	1	2	4	2		b.	Illı	(OR) strate the sensor and its different types with real time examples.	10	2	1	2,
	<ul><li>(A) Floor planning</li><li>(C) Testing</li></ul>	<ul><li>(B) Placement and routing</li><li>(D) Extraction</li></ul>						27. a.	Illı	astrate the $PSOC_3$ architecture with a neat block diagram.	10	3	2	1,
18.	Which attribute in synthesis process the quantity of current it can source?  (A) Load attribute  (C) Combinational attribute	s specify the resistance by controlling  (B) Drive attribute  (D) Sequential attribute	1	2	4			b.	Ex	(OR) plain in detail about power management and internal regulators.	10	3	2	2,

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